Regarding the change of names mentioned in the document, such as Mitsubishi Electric and Mitsubishi XX, to Renesas Technology Corp.

The semiconductor operations of Hitachi and Mitsubishi Electric were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Mitsubishi Electric, Mitsubishi Electric Corporation, Mitsubishi Semiconductors, and other Mitsubishi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

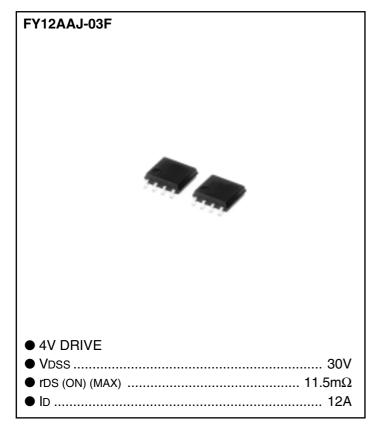
Note: Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

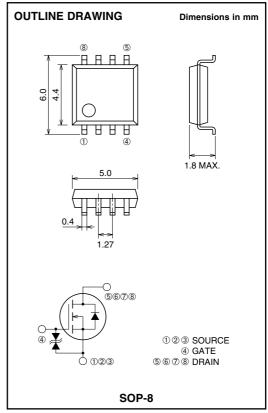
Renesas Technology Corp. Customer Support Dept. April 1, 2003



FY12AAJ-03F

HIGH-SPEED SWITCHING USE





APPLICATION

Motor control, Lamp control, Solenoid control DC-DC converter, etc.

MAXIMUM RATINGS (Tc = 25°C)

Symbol	Parameter	Conditions	Ratings	Unit
VDSS	Drain-source voltage	VGS = 0V	30	٧
Vgss	Gate-source voltage	VDS = 0V	±20	V
ID	Drain current		12	Α
IDM	Drain current (Pulsed)		84	Α
IDA	Avalanche drain current (Pulsed)	$L = 10\mu H$	12	Α
Is	Source current		1.8	Α
Ism	Source current (Pulsed)		7.2	Α
PD	Maximum power dissipation		2.0	W
Tch	Channel temperature		−55~+150	Ŝ
Tstg	Storage temperature		− 55~+150	ç
_	Weight	Typical value	0.07	g



FY12AAJ-03F

HIGH-SPEED SWITCHING USE

ELECTRICAL CHARACTERISTICS (Tch = 25°C)

Symbol	Parameter	Test conditions		Limits		
			Min.	Тур.	Max.	Unit
V (BR)DSS	Drain-source breakdown voltage	ID = 1mA, VGS = 0V	30	_	_	V
V (BR)GSS	Gate-source breakdown voltage	$IG = \pm 100 \mu A$, $VGS = 0V$	±20	_	_	V
IDSS	Drain-source leakage current	VDS = 30V, VGS = 0V	T -	_	0.1	mA
Igss	Gate-source leakage current	$VGS = \pm 20V$, $VDS = 0V$		_	±10	μΑ
VGS (th)	Gate-source threshold voltage	ID = 1mA, VDS = 10V	1.0	1.5	2.0	V
rDS (ON)	Drain-source on-state resistance	ID = 12A, VGS = 10V		9.0	11.5	mΩ
rDS (ON)	Drain-source on-state resistance	ID = 6A, VGS = 4.5V	_	12.5	17.5	mΩ
rDS (ON)	Drain-source on-state resistance	ID = 6A, VGS = 4V	T -	14.5	20.0	mΩ
VDS (ON)	Drain-source on-state voltage	ID = 12A, VGS = 10V	T -	0.108	0.138	V
l yfs l	Forward transfer admittance	ID = 12A, VDS = 10V	_	25	_	S
Ciss	Input capacitance	VDS = 10V, VGS = 0V, f = 1MHz	_	1800	_	pF
Coss	Output capacitance		_	500	_	pF
Crss	Reverse transfer capacitance		_	230	_	pF
td (on)	Turn-on delay time	$VDD = 15V$, $ID = 6A$, $VGS = 10V$, $RG = 5\Omega$		18	_	ns
tr	Rise time		_	20	_	ns
td (off)	Turn-off delay time		_	50	_	ns
tf	Fall time		_	17	_	ns
Qg	Total gate charge	VDD = 15V, VGS = 10V, ID = 12A	_	35	_	nC
Qgs	Gate-source charge		_	4	_	nC
Qgd	Gate-drain charge		_	10	_	nC
VsD	Source-drain voltage	Is = 1.8A, VGS = 0V	_	0.75	1.10	V
Rth (ch-a)	Thermal resistance	Channel to air	_	_	62.5	°C/W
trr	Reverse recovery time	Is = 1.8A, $dis/dt = -50A/\mu s$	T -	45	_	ns